



NEWS RELEASE

Credo to Showcase High-Speed Connectivity Innovations Driving Next-Generation AI Infrastructure at AI Infra 2026

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SAN JOSE, Calif.--(BUSINESS WIRE)-- **Credo Technology Group Holding Ltd** (Credo) (NASDAQ: CRDO), an innovator in providing connectivity at scale through fast, reliable, and energy-efficient system solutions, will showcase its newest optical and copper interconnect products for scaling AI infrastructure at AI Infra Summit 2026. AI Infra Summit 2026 takes place September 15-17 at the Santa Clara Convention Center in Santa Clara, California.

Credo Booth Demonstration Highlights (Booth #810)

- **ZeroFlap Optics:** The latest transceivers in the ZeroFlap Optics family built for reliability at AI scale, delivering the bandwidth and operational stability required for large AI deployments.
- **800G ZeroFlap Optics + PILOT:** High-performance optical connectivity paired with real-time link telemetry through the Credo PILOT observability platform, providing enhanced visibility into network health and performance.
- **1.6T ZeroFlap Active Electrical Cable(AEC) + PILOT:** Advanced AEC solution delivering high-speed AI interconnects with telemetry, diagnostics, and fault analysis capabilities through PILOT.
- **Toucan Gen6 PCIe AEC + PILOT:** PCIe connectivity solution providing real-time telemetry and rapid fault isolation for GPU-intensive AI workloads.

Panels and Presentations:

- **Panel: Scale-Out: Network Architectures for Accelerating Distributed AI Workloads at Scale**
September 15 at 2:20 p.m. as part of the Data Movement Track

Credo Speaker: Don Barnetson, Senior Vice President of Product

- Presentation: Breaking the AI Inference Memory Wall with Credo OmniConnect
September 16 at 11:30 a.m. in Expo Theater 2

Credo Speaker: Vishal Shah, Vice President of Product

- Presentation: ZeroFlap Optics: Scaling Reliability with Bandwidth
September 17 at 11:00 a.m. as part of the Compute Track

Credo Speaker: Rajan Pai, Vice President of Optical Solutions

To request a meeting or product demo, please contact sales@credosemi.com.

About Credo

Credo's mission is to transform connectivity at scale through fast, reliable, and energy-efficient system solutions. Our high-speed copper and optical interconnect technologies deliver industry-leading power and performance from chip to cluster to meet the ever-expanding data infrastructure demands of AI.

Our vertically integrated connectivity portfolio is comprised of our flagship purple ZeroFlap (ZF) Active Electrical Cables (AECs) and ZF optical transceivers; optical components including silicon photonics-based photonic integrated circuits (SiPho PICs) and DSPs; OmniConnect AI memory and chip-to-chip interconnect; and retimers for Ethernet and PCIe—supported by our PILOT diagnostic and analytics software platform. Credo innovations enable our customers to connect the systems that connect the world.

For more information, please visit <https://www.credosemi.com>. Follow Credo on [LinkedIn](#).

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